

### Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Green Device Available

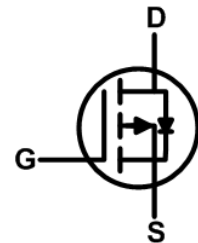
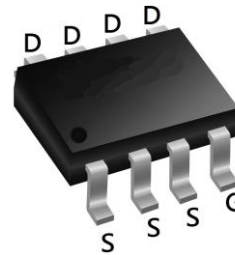
### Product Summary

BVDSS	RDSON	ID
-150V	780mΩ	-1.1A

### Applications

- Load Switch.
- Power Management.
- LED Backlighting.
- Networking application.

### SOP-8 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-1.1	A
$I_D @ T_A = 70^\circ\text{C}$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-0.88	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-4.4	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	12.5	mJ
$I_{AS}$	Avalanche Current	5	A
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	40	$^\circ\text{C/W}$

## Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-150	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-1A	---	650	780	mΩ
		V <sub>GS</sub> =-6V , I <sub>D</sub> =-0.5A	---	700	980	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-2.0	-3.0	-4.0	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-120V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =-120V , V <sub>GS</sub> =0V , T <sub>J</sub> =85°C	---	---	30	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	12	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-75V , V <sub>GS</sub> =-10V , I <sub>D</sub> =-1A	---	10.8	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	3.1	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	2.2	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-30V , V <sub>GS</sub> =-10V , R <sub>G</sub> =6Ω, I <sub>D</sub> =-1A	---	21	---	ns
T <sub>r</sub>	Rise Time		---	16	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	40	---	
T <sub>f</sub>	Fall Time		---	18	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-75V , V <sub>GS</sub> =0V , f=1MHz	---	706	---	pF
C <sub>oss</sub>	Output Capacitance		---	23	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	13	---	
Diode Characteristics						
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	-1	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=-50V, V_{GS}=-10V, L=1mH, I_{AS}=-5A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_S$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

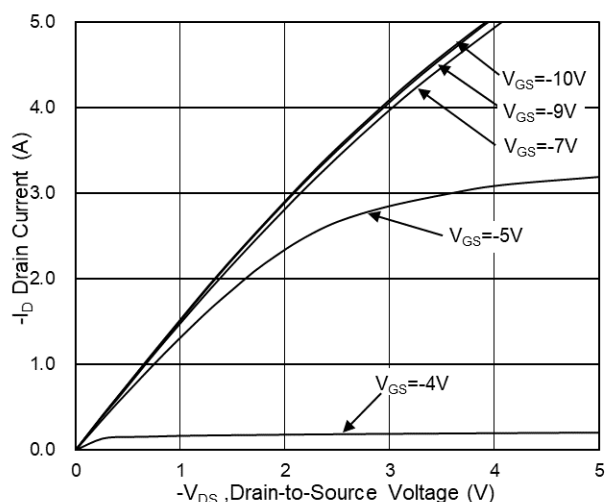


Fig.1 Typical Output Characteristics

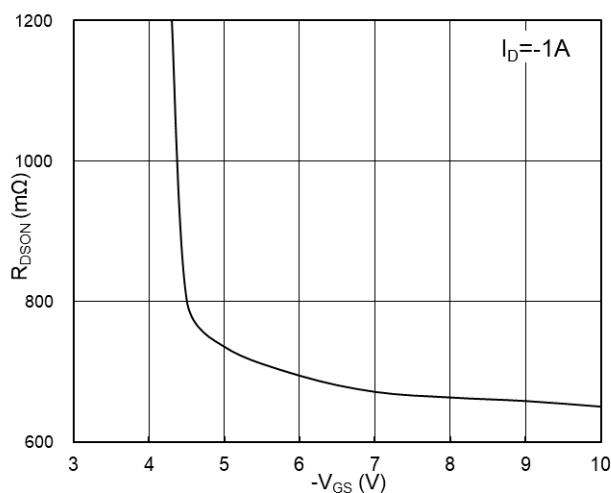


Fig.2 On-Resistance vs G-S Voltage

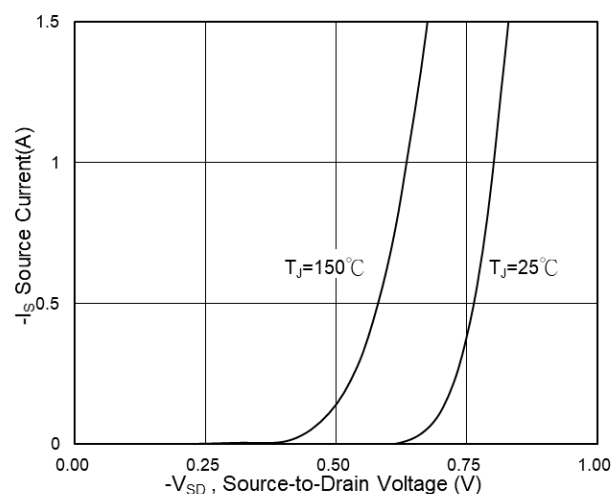


Fig.3 Source Drain Forward Characteristics

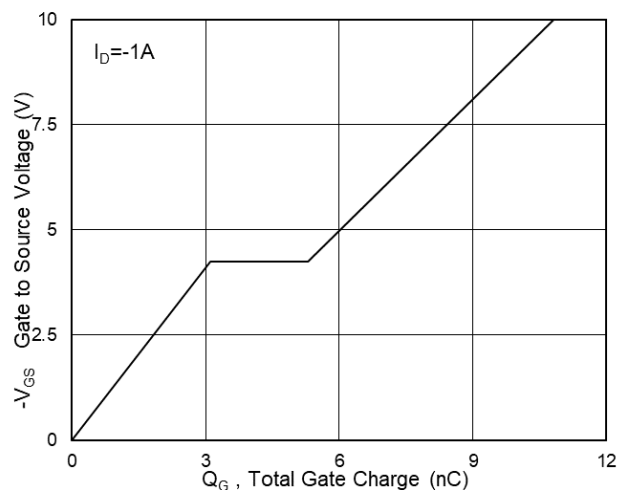


Fig.4 Gate-Charge Characteristics

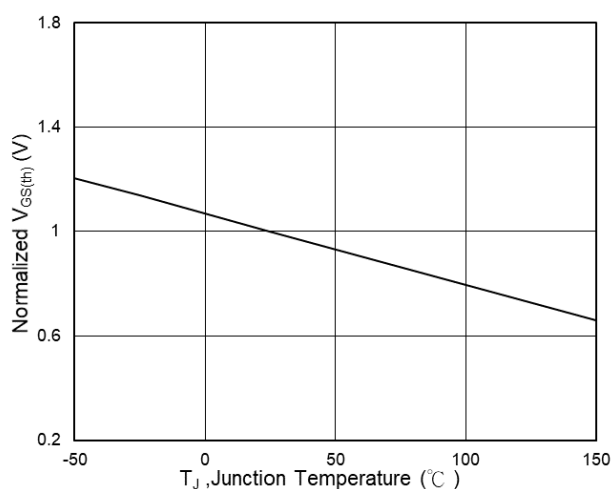


Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$

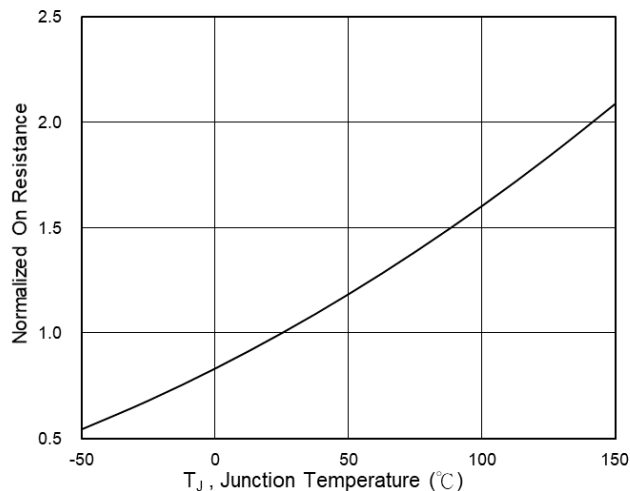
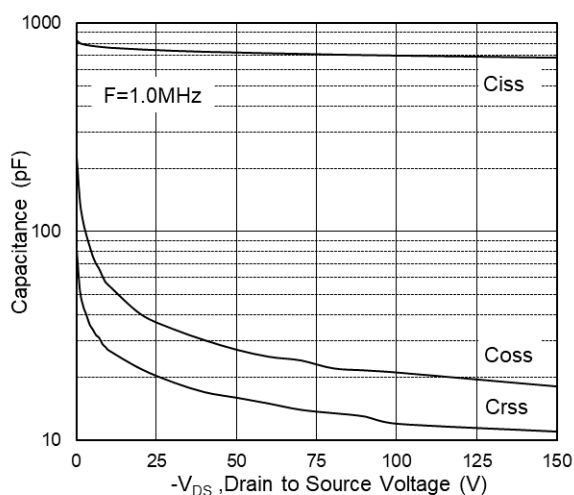
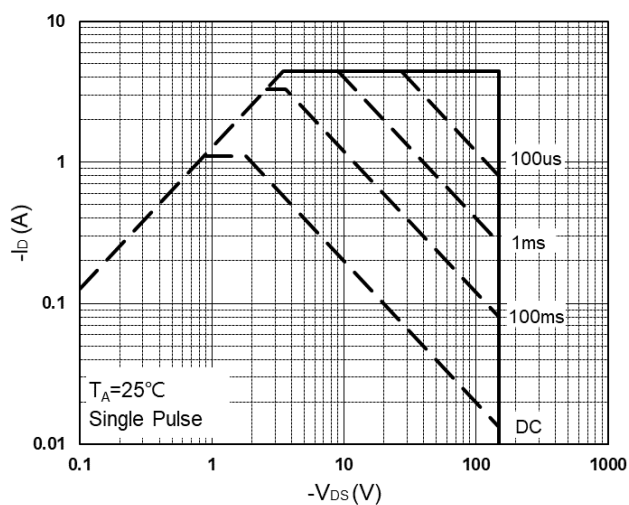


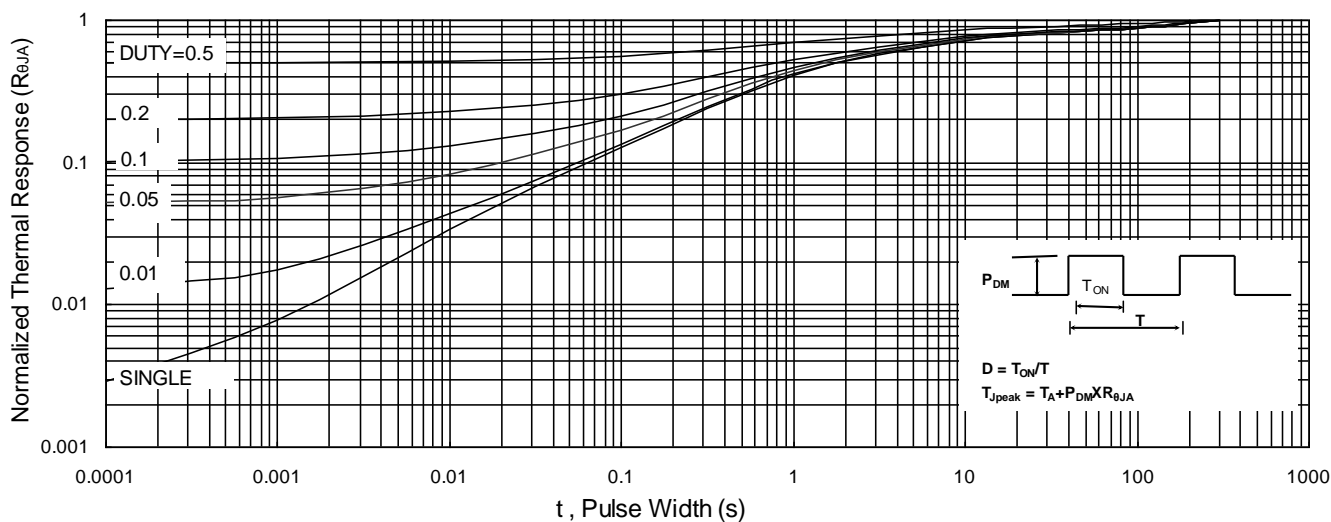
Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$



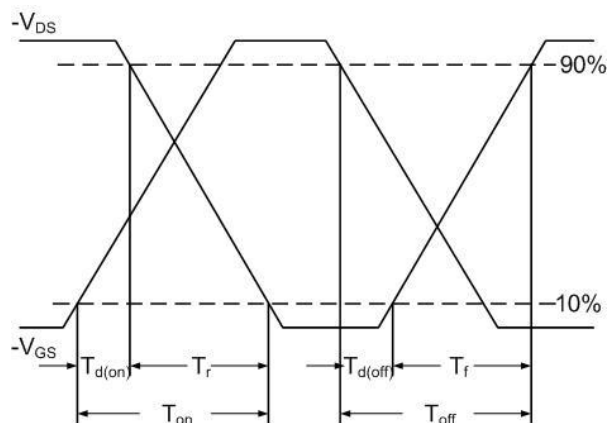
**Fig.7 Capacitance**



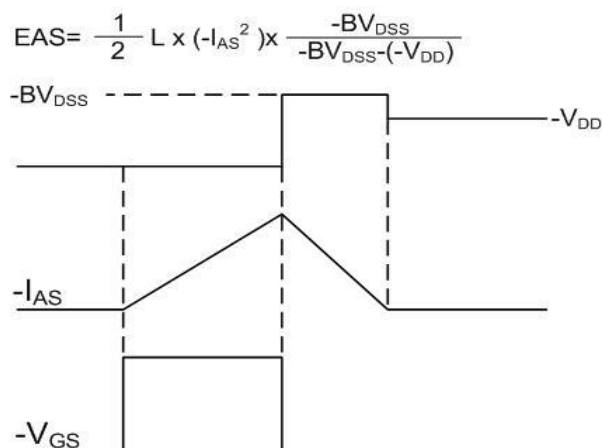
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

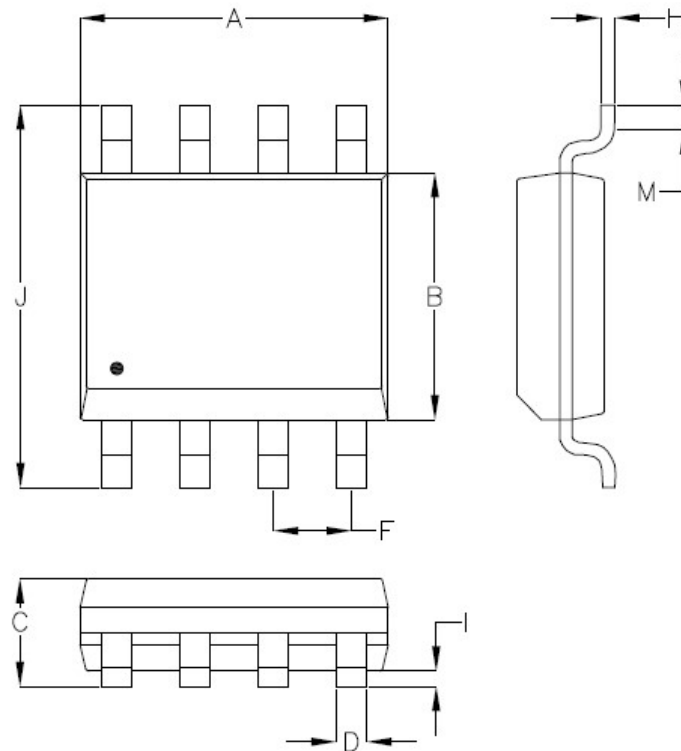


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

## SOP-8L Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.700	5.150	0.185	0.203
B	3.700	4.100	0.146	0.161
C	1.23	1.753	0.048	0.069
D	0.310	0.510	0.012	0.020
F	1.070	1.470	0.042	0.058
H	0.160	0.254	0.006	0.010
I	0.050	0.254	0.002	0.010
J	5.750	6.250	0.226	0.246
M	0.400	1.270	0.016	0.050

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